

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A silicone rubber adhesive composition used for forming an integrally molded article with an organic resin comprising

(A) 100 parts by weight of a heat curable organopolysiloxane composition,

(B) 1 to 100 parts by weight of reinforcing silica fines, and

(C) 0.1 to 50 parts by weight of an organic compound or organosilicon compound having an epoxy equivalent of 100 to 5,000 g/mol and containing at least one aromatic ring in a molecule

the cured product of said silicone rubber adhesive composition providing a greater bond strength to said organic resin than any mold used for forming the integrally molded article.

2. (Currently Amended) The composition of claim 1 wherein compound component (C) is an organosilicon compound containing at least one Si-H group in a molecule.

3. (Original) The composition of claim 1 which provides a greater bond strength to organic resins than to metals.

4. (Original) An integrally molded article comprising a silicone rubber adhesive composition in the cured state and a thermoplastic resin, said silicone rubber adhesive composition comprising

(A) 100 parts by weight of a heat curable organopolysiloxane composition,

(B) 1 to 100 parts by weight of reinforcing silica fines, and

(C) 0.1 to 50 parts by weight of an organic compound or organosilicon compound having an epoxy equivalent of 100 to 5,000 g/mol and containing at least one aromatic ring in a molecule.

5. (Currently Amended) An The integrally molded article ~~of claim 4~~ comprising a silicone rubber adhesive composition in the cured state and a thermoplastic resin, said silicone rubber adhesive composition comprising:

(A) 100 parts by weight of a heat curable organopolysiloxane composition,

(B) 1 to 100 parts by weight of reinforcing silica fines, and

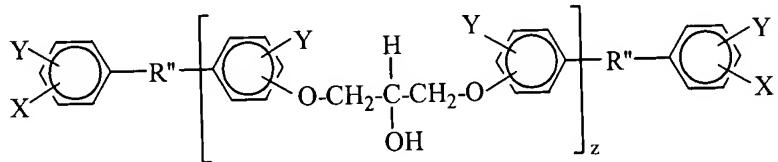
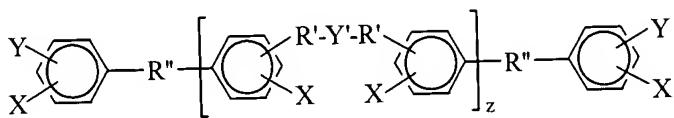
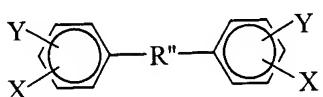
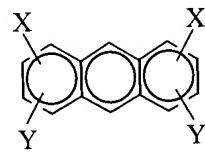
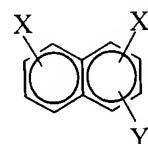
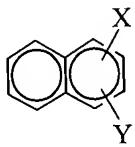
(C) 0.1 to 50 parts by weight of an organic compound or organosilicon compound having an epoxy equivalent of 100 to

5,000 g/mol and containing at least one aromatic ring in a molecule

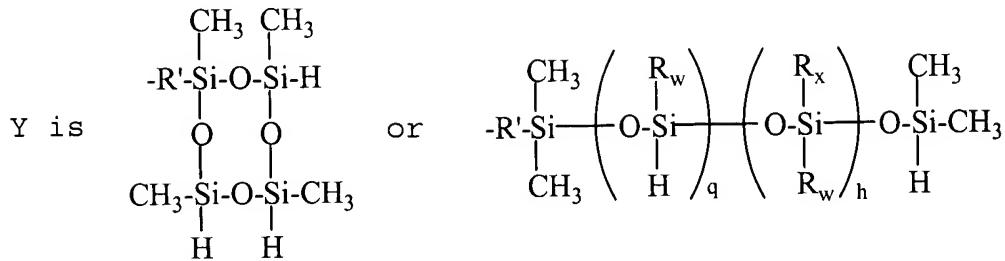
wherein compound component (C) is an organosilicon compound containing at least one Si-H group in a molecule.

6. (New) The composition of claim 1 wherein compound (C) is the organosilicon compound having at least one linear or cyclic siloxane structure.

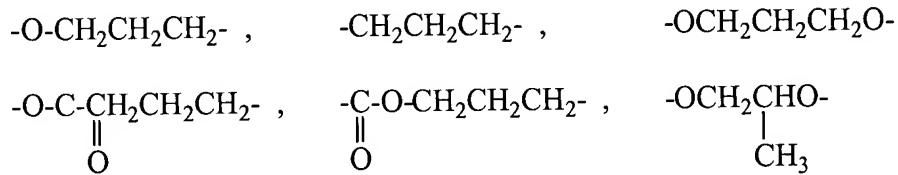
7. (New) The composition of claim 1 or wherein compound (C) is at least one selected from the compounds of the following formulae:



wherein X is $-\text{O}-\text{CH}_2-\text{CH}(\text{O})-\text{CH}_2$

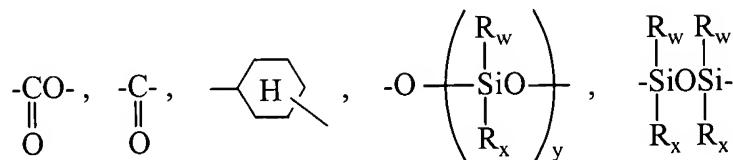
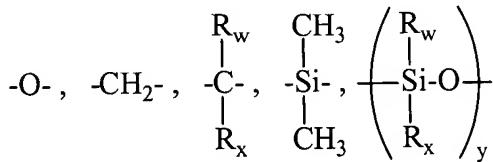


wherein R' is selected from the following groups:



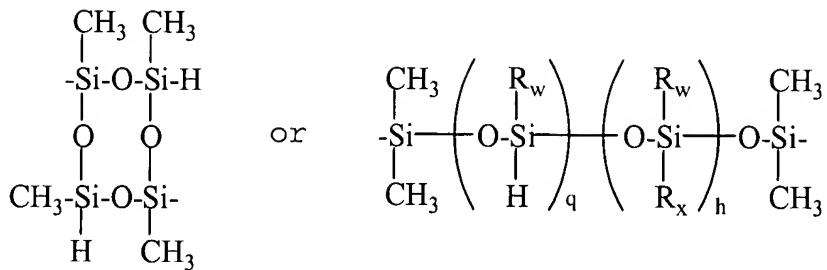
h
R_w and R_x are substituted or unsubstituted monovalent hydrocarbon groups, q is a number of 1 to 50, and h is a number of 0 to 50,

R" is selected from the following groups:



wherein R_w and R_x are as defined above, and y is a number of 0 to 100, and

Y' is



wherein R_w , R_x , q and h are as defined above. Subscript z is a number of 1 to 10.

8. (New) The composition of claim 1 wherein the organopolysiloxane composition comprises a diorganopolysiloxane of a straight chain structure whose backbone comprises recurring diorganosiloxane units of the formula: $\text{R}^1_2\text{SiO}_{2/2}$ and which is blocked with a triorganosiloxy group of the formula: $\text{R}^1_3\text{SiO}_{1/2}$ at either end

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wherein R^1 is a substituted or unsubstituted monovalent hydrocarbon group of 1 to 12 carbon atoms.

9. (New) The composition of claim 1 wherein the organopolysiloxane composition comprises a diorganopolysiloxane has a weight average degree of polymerization of about 10 to 10,000.